



DS-10P Parquet Adhesive

Revision: 19/03/2020

Page 1 from 2

Technical data

Basis	Vinyl acetate/Ethylene homopolymer
Consistency	Paste
Curing system	Physical drying
Density	Ca. 1,48 g/ml
Temperature resistance**	-20°C till +70°C (cured)
Open time	30 - 45 minutes
Adjustable until	25 - 30 minutes
Sandable/Paintable after	Min. 24h (in combination with nailing) Min. 48h (without nailing)
Resistance against aging	Good
Application temperature	5 °C → 30 °C
Consumption (*)	500-1000 g/m ² Depending on the surface and trowel

* These values may vary depending on environmental factors such as temperature, moisture, and type of substrates. ** This information relates to fully cured product.

Product description

DS-10P Parquet Adhesive is a ready to use solvent-free dispersion parquet adhesive. Suitable for bonding most common types of parquet onto highly absorbent substrates and also tapis floors on wooden subfloors.

Properties

- Easy to tool
- Professional quality
- High adhesive strength
- Long open time
- Elastic adhesive layer
- High end strength (shear strength according EN14293)
- Hard elastic

Applications

- DS-10P Parquet Adhesive is suitable for indoor bonding of many types of wooden floors such as mosaic, wood or laminate parquet (up to max. 250 x 50 mm), tapis 6-8 mm (in combination with nails), multi-layer or pre-finished parquet and laminates.
- Not suitable for bonding beech (and), moisture sensitive or exotic wood (hard wood).

- Suitable for indoor use on highly absorbent subfloors of wood, chipboard or OSB Board (large particle size chipboard) in combination with nails.

Packaging

Colour: light brown
Packaging: 15 kg bucket

Shelf life

At least 12 months in unopened packaging in a dry storage place at temperatures between +5 °C and +25 °C.

Substrates

Substrates: porous substrates like concrete and wood
Nature: DS-10P Parquet Adhesive should be applied on a rigid, clean, permanently dry, dust and grease free surface which do not contain any loose parts, paint, wax, oil or other contaminants. Irregularities such as remaining concrete leveling, old adhesives may adversely affect adhesion. These need preferably to be removed mechanically for example by sanding or blasting.

Surface preparation: No pretreatment required. Before installation of the parquet, the substrate should be checked to ensure it is suitable.

Remark: This technical data sheet replaces all previous versions. The directives contained in this documentation are the result of our experiments and of our experience and have been submitted in good faith. Because of the diversity of the materials and substrates and the great number of possible applications which are out of our control, we cannot accept any responsibility for the results obtained. Since the design, the quality of the substrate and processing conditions are beyond our control, no liability under this publication is accepted. In every case it is recommended to carry out preliminary experiments. Soudal reserves the right to modify products without prior notice.

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Revision: 19/03/2020

Page 2 from 2

Check the moisture content throughout the entire thickness of the substrate with a carbide or electric hygrometer. Note that an electric hygrometer only gives indicative values. The moisture content must correspond the recommendation of the floor manufacturer (generally max. 2% for sand cement substrates and max. 0,5% for anhydrite, measured with a carbide hygrometer. For substrates with underfloorheating the values are resp. max. 1,5% and 0,3%). Do not use DS-10P Parquet Adhesive on substrates, which contain anhydrite or magnesium. Use Soudal MS-30P for these substrates.

DS-10P Parquet Adhesive should be applied to an even, dry, clean and smooth substrate, which is also free from paint, wax, oil, irregularities and cracks. We recommend a preliminary adhesion test on any substrate.

Parquet

The parquet flooring must be acclimatised for several days in the area where it is to be installed. Leave the parquet in its original packaging until installation to avoid any deformation. Check before installation that the moisture content of the wood is as recommended by the supplier, (generally 9% +/- 2%). If the humidity of the wood is more than 11% installation is not recommended. Allow a gap of 1 to 1,5 cm around the perimeter of the laid parquet, including any columns or structures, which penetrate the floor.

Application method

DS-10P Parquet Adhesive should be acclimatised to room temperature before installation. Apply the adhesive by means of SOUDAL notched trowel N° 3 to the surface. Do not apply more to the surface than can be covered with parquet within 30 minutes. Slide the parquet onto the adhesive layer and tap into place or tamp down with a rubber hammer. A minimum of 80% contact coverage is required to ensure the adhesion of the parquet. If necessary load the parquet with

weight. When bonding tapis onto a wooden subfloor the parquet must also be nailed. Wait at least 48 hours before sanding and finishing the parquet. In case of bonded and nailed tapis, wait at least 24 hours.

Cleaning: Before curing, DS-10P Parquet Adhesive can be removed with water from substrates and tools. Cured DS-10P Parquet Adhesive can only be removed mechanically.

Health- and Safety Recommendations

Take the usual labour hygiene into account. Consult label and material safety data sheet for more information.

Remarks

- Never apply on a substrate which is not protected against rising damp. If necessary apply a moisture sealer such as Soudal EPR-31P.
- Do not apply at temperatures below 15° or above 25°C.
- Minimum temperature of the substrate should be at least 15°C.
- Do not apply the adhesive when the relative humidity is above 75%.
- Never install flooring on a substrate which contains too much moisture or on substrates with a higher humidity value than recommended by the wood supplier.
- Never install wood which is too dry (<7% humidity). It can expand at higher humidity and cause damage.
- Do not install if the walls and ceilings of the area are not dry (e.g. after plastering or painting etc.)
- Do not dilute the adhesive.

Leed regulation:

DS-10P Parquet Adhesive conforms to the requirements of LEED. Low –Emitting Materials: Adhesives and Sealants. SCAQMD rule 1168. Complies with USGBC LEED 2009 Credit 4.1: Low-Emitting Materials – Adhesives & Sealants concerning the VOC-content. VOS-level < 50 g/L

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